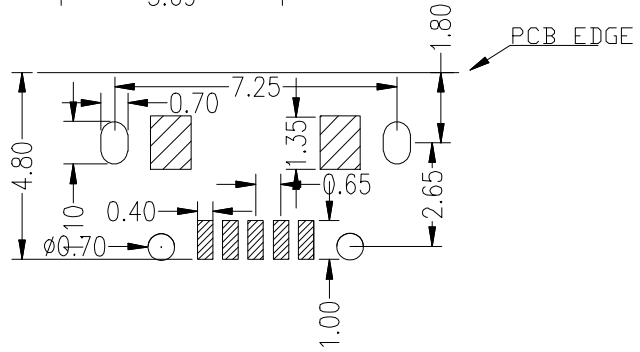
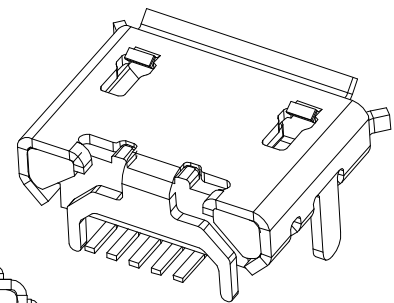
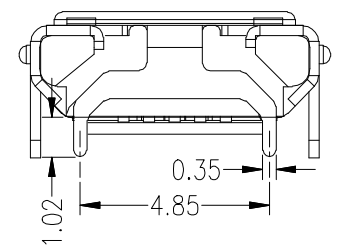
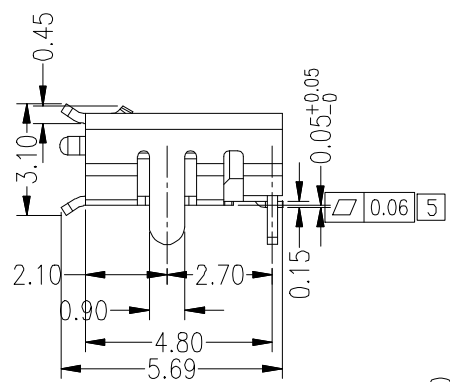
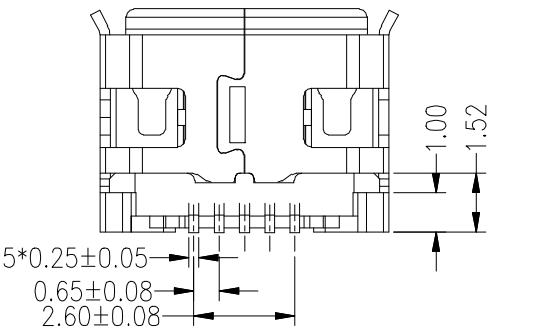
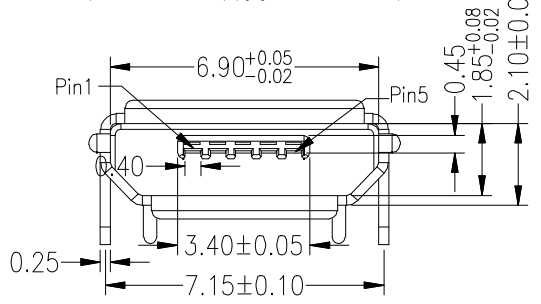
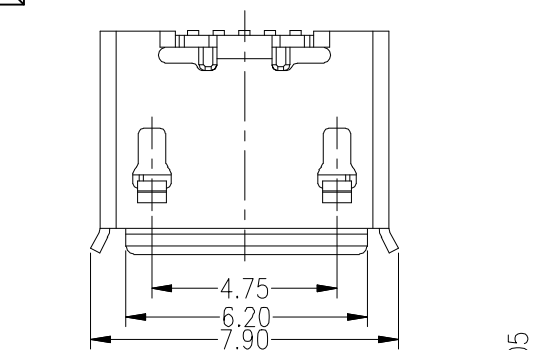


REV	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		



- Note:
- Material:
    - Housing: High temperature thermoplastic with g.f,UL94v-0
    - Contact: copper alloy,t=0.15mm
    - Shell: copper alloy,t=0.30mm
  - Specification:
    - Current rating: 1 A Max.
    - Dielectric withstanding voltage: 100 V(ac) for 1 min.
    - Contact resistance: 50 mW Max.
    - Insulation resistance: 100 MW Min.
    - Total mating force: 3.57 Kgf Max.
    - Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
    - Temperature range: -30°C~80°C

A 01 Y W X X X X X X X - 041  
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

外壳材质  
1:C2680R-H

端子电镀01:Ni+Au1u'' ;02:Au1.5u'' ;03:Au3u''

主体颜色B:黑色

主体材质2:尼龙 9T

端子材质4:C2680R-EH

外壳电镀  
1:Ni100u''  
2:Sn100u''  
3:Ni+Au1u'' (脚)

DESIGN:	Xiping Huang			
CHECK:	Ke Tian			
APPROVED:	Youquan Xu			
DIM	TOL	DIM	TOL	
X.	±0.25	X°	±3.0°	
X.X	±0.20	X.X°		
X.XX	±0.15	X.XX°		
X.XXX		X.XXX°		

**QWYCONN** 深圳市启崧源电子有限公司  
 SHENZHEN QIWEIYUAN ELECTRONIC CO., LTD.

TITLE:  
**Micro usb 5P 插板4.85 牛角脚长1.1四脚全插有卷边**

PART NO.

REV. A	SCALE: N/A	UNIT: mm	SHEET: 1/1	
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